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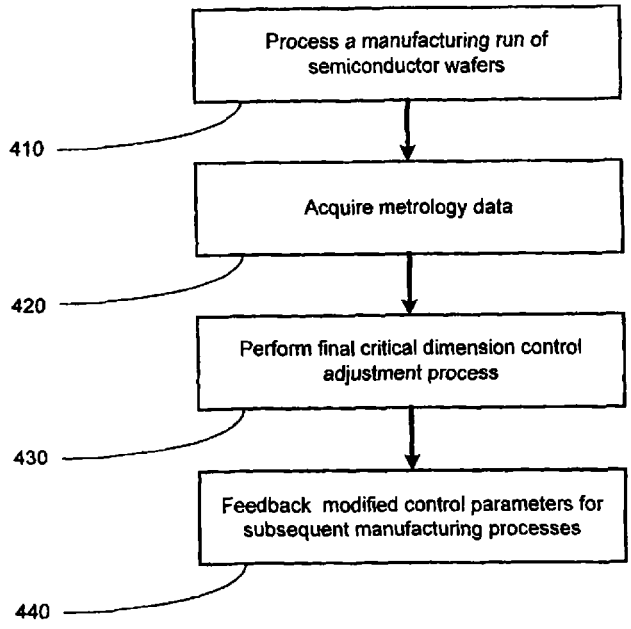
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(54) Title: METHOD AND APPARATUS FOR PERFORMING FINAL CRITICAL DIMENSION CONTROL

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(57) Abstract: The present invention provides for a method and an apparatus for control of final critical dimensions during processing of semiconductor wafers (105). A manufacturing run of semiconductor wafers (105) is processed. Metrology data from the processed semiconductor wafers (105) is acquired. A final critical dimension control adjustment process is performed using the acquired metrology data. A feedback/feed-forward modification process is performed in response to the final critical dimension control adjustment process.

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